NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203 x .008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
   250 TO 300 MICROINCHES (2.5um-7.6um) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICROINCHES (1um-2um) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

SECTION A-A

DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:

ANGULAR: 0.5 DEGREE
.X: 0.76
.XX: 0.25
.XXX: 0.13
.XXXX: 0.01

MATERIAL
SEE NOTE 1

FINISH
SEE NOTE 2

THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF
QPTECHNOLOGIES. ANY REPRODUCTION IN PART OR AS A WHOLE
WITHOUT THE WRITTEN PERMISSION OF QPTECHNOLOGIES IS PROHIBITED.

UNLESS OTHERWISE SPECIFIED

NAME
DATE
DRAWN
CHECKED
ENG APPR.

S. Swen
8/1/11
S. Swen
8/1/11
S. Swen
8/1/11

COMMENTS

PROPERTY AND CONFIDENTIAL

Drawing Scale: 12:1

Sheet 1 of 1

500376